

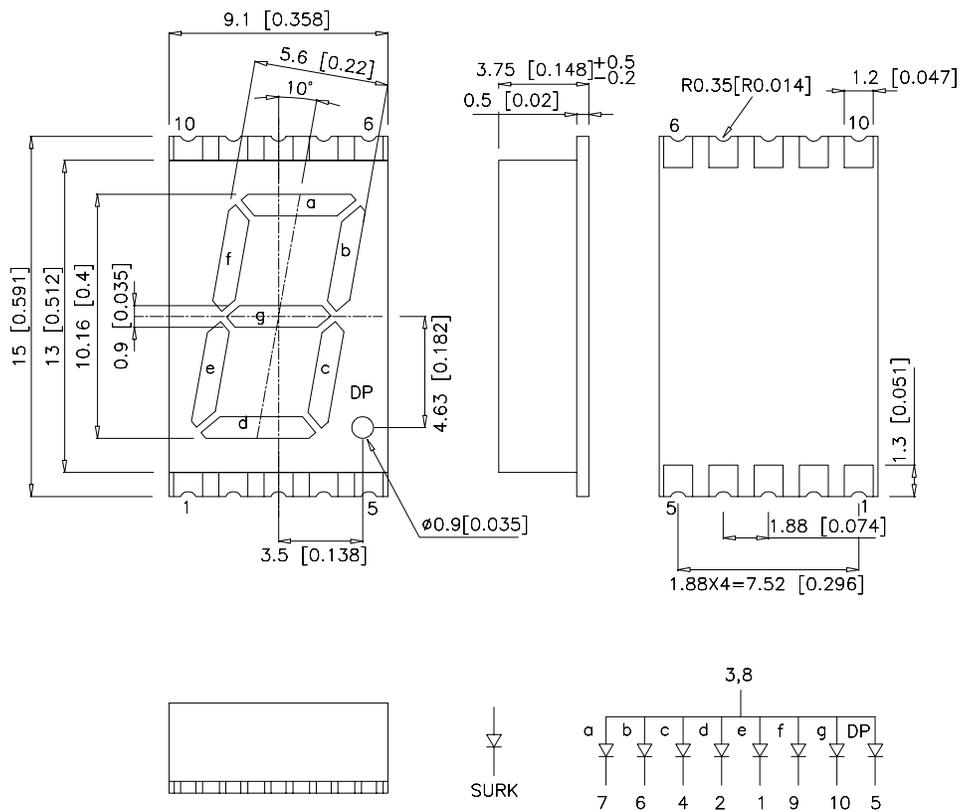
Features

- 0.4INCH DIGIT HEIGHT.
- LOW CURRENT OPERATION.
- EXCELLENT CHARACTER APPEARANCE.
- I.C. COMPATIBLE
- MECHANICALLY RUGGED.
- GRAY FACE, WHITE SEGMENT.
- PACKAGE : 900PCS/REEL.

Description

The Hyper Red source color devices are made with DH InGaAlP on GaAs substrate Light Emitting Diode.

Package Dimensions & Internal Circuit Diagram



Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) @ 10 mA		Description
			Min.	Typ.	
APSA04-41SURKWA	HYPER RED(InGaAlP)	WHITE DIFFUSED	12	26	Common Anode,Rt. Hand Decimal

Electrical / Optical Characteristics at T_A=25°C

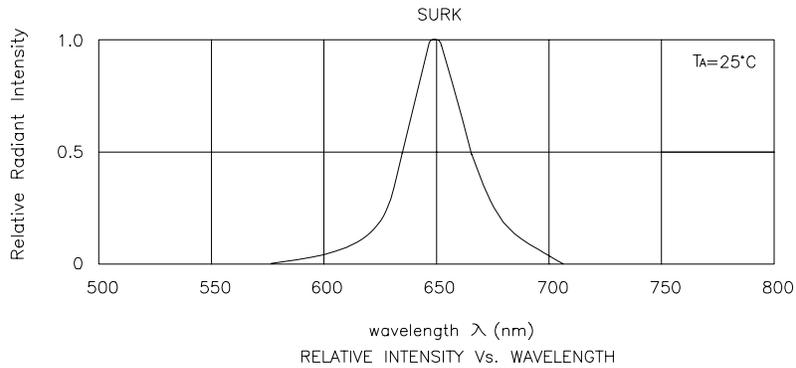
Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λ_{peak}	Peak Wavelength	Hyper Red	650		nm	I _F =20mA
λ_D	Dominant Wavelength	Hyper Red	635		nm	I _F =20mA
$\Delta\lambda_{1/2}$	Spectral Line Half-width	Hyper Red	28		nm	I _F =20mA
C	Capacitance	Hyper Red	35		pF	V _F =0V;f=1MHz
V _F	Forward Voltage	Hyper Red	1.95	2.5	V	I _F =20mA
I _R	Reverse Current	Hyper Red		10	μA	V _R = 5V

Absolute Maximum Ratings at T_A=25°C

Parameter	Hyper Red	Units
Power dissipation	170	mW
DC Forward Current	30	mA
Peak Forward Current [1]	185	mA
Reverse Voltage	5	V
Operating/Storage Temperature	-40°C To +85°C	

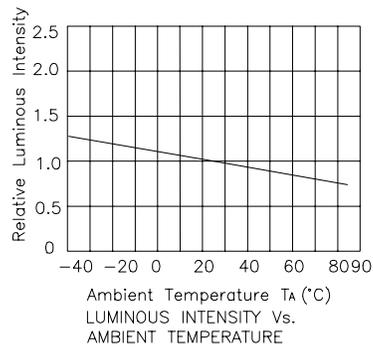
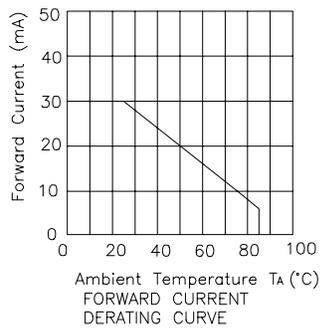
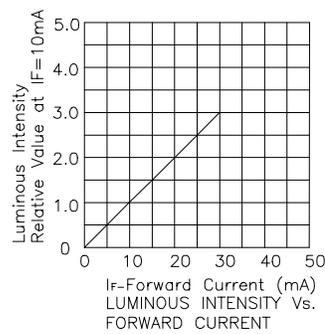
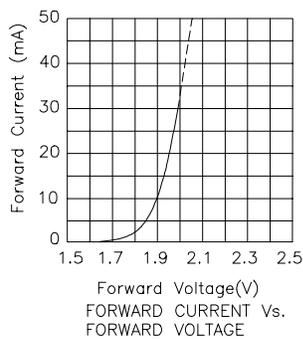
Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.



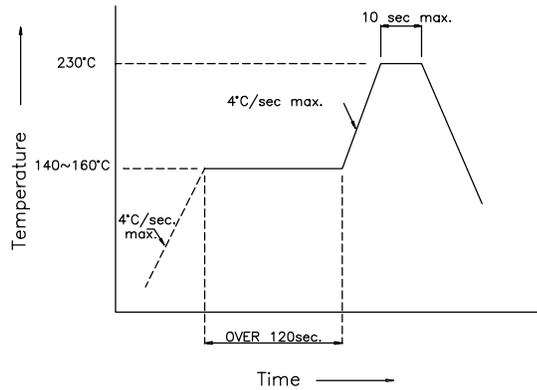
Hyper Red

APSA04-41SURKWA

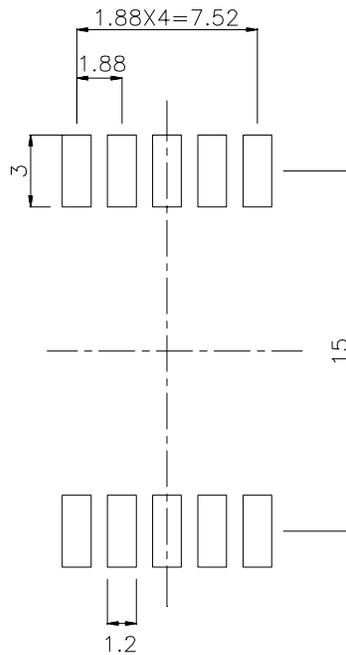


APSA04-41SURKWA SMT Reflow Soldering Instructions

Number of reflow process shall be less than 2 times and cooling process to normal temperature is required between first and second soldering process.



Recommended Soldering Pattern (Units : mm)



Tape Specifications (Units : mm)

